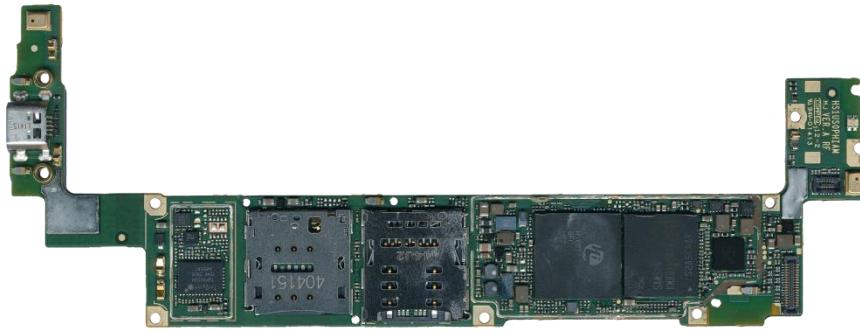




# Huawei Ascend P7-L00



## Teardown Analysis Report

To Know





# Huawei Ascend P7-L00 Product Analysis Report

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